

# MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



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MOV



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PLED

## GBU6005-MS THRU GBU610-MS

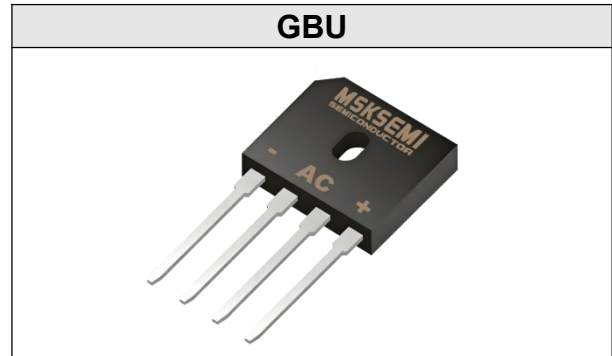
Product specification

**VOLTAGE RANGE: 50 - 1000V**  
**CURRENT: 6.0 A**

## FEATURES

- Ideal for printed circuit board
- Low forward voltage
- Low leakage current
- Polarity: marked on body
- Mounting position: Any

## REFERENCE NEWS



## Marking

GBU6005-MS	GBU601-MS	GBU602-MS	GBU604-MS
GBU606-MS	GBU608-MS	GBU610-MS	

## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified. Single phase half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

TYPE NUMBER	GBU6005-MS	GBU601-MS	GBU602-MS	GBU604-MS	GBU606-MS	GBU608-MS	GBU610-MS	UNITS
Maximum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current. 375"(9.5mm) Lead Length at Tc=100°C	6.0							A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	150							A
Maximum Forward Voltage Drop per Bridge Element at 3.0A D.C.	1.0							V
Maximum DC Reverse Current at Ta=25°C	5							µA
Rated DC Blocking Voltage Ta=100°C	500							µA
Operating Temperature Range, Tj	-65 to + 150							°C
Storage Temperature Range, TSTG	-65 to + 150							°C

## RATING AND CHARACTERISTIC CURVES (GBU6005-MS THRU GBU610-MS)

FIG.1-TYPICAL FORWARD CURRENT  
DERATING CURVE

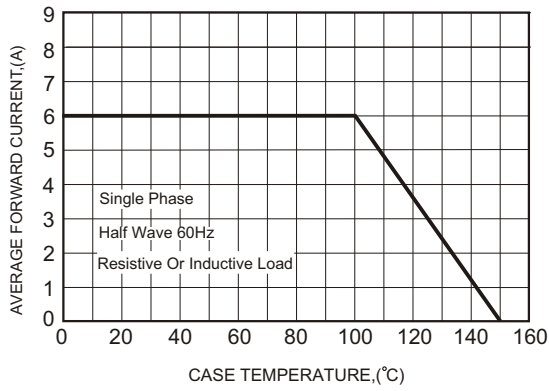


FIG.2-MAXIMUM NON-REPETITIVE FORWARD  
SURGE CURRENT

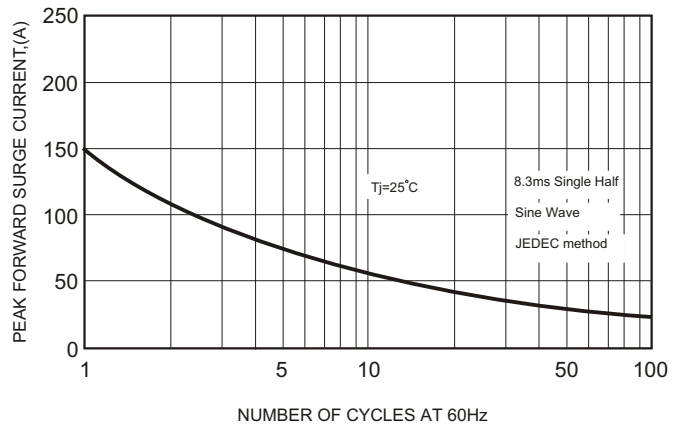


FIG.3-TYPICAL FORWARD  
CHARACTERISTICS

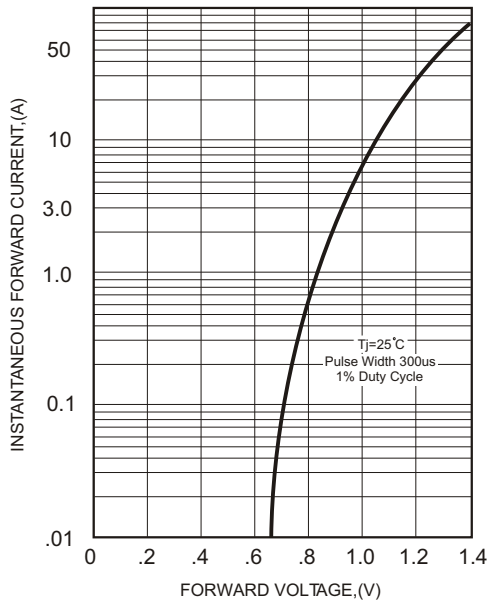
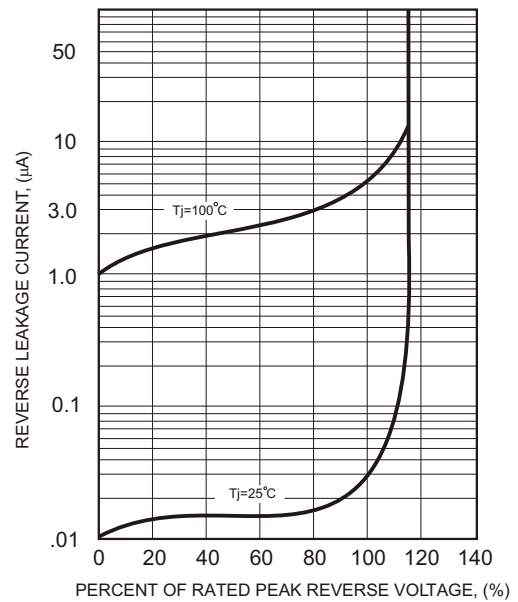
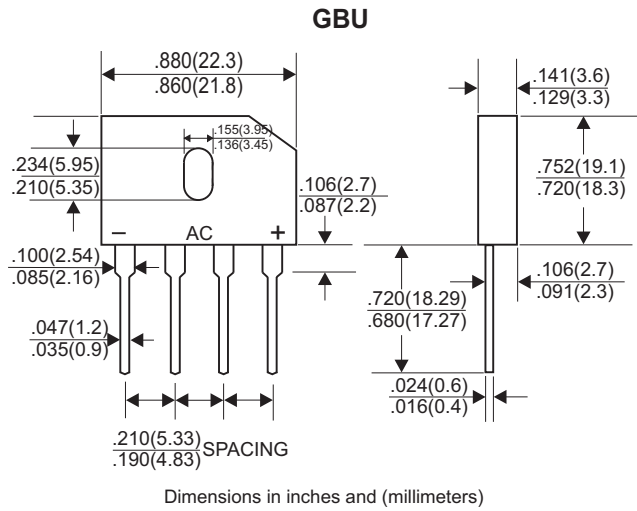


FIG.4-TYPICAL REVERSE  
CHARACTERISTICS



**PACKAGE MECHANICAL DATA**



**REELSPECIFICATION**

P/N	PKG	QTY
GBU6005-MS THRU GBU610-MS	GBU	500

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